

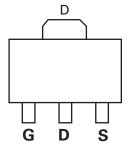
N-Channel 60-V (D-S) MOSFET

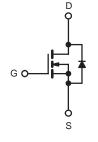
| PRODUCT SUMMARY | | | | | | | |
|---------------------|----------------------------------|--------------------|--|--|--|--|--|
| V _{DS} (V) | R _{DS(on)} (Ω) | I _D (A) | | | | | |
| 60 | 0.030 at V _{GS} = 10 V | 8.0 | | | | | |
| | 0.034 at V _{GS} = 4.5 V | 6.5 | | | | | |

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- Trench Power MOSFETs
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

| Parameter | Symbol | 10 s | Steady State | Unit | |
|---|-----------------------------------|----------------|--------------|------|----|
| Drain-Source Voltage | V _{DS} | 6 | V | | |
| Gate-Source Voltage | V _{GS} | ± | | | |
| Continuous Drain Current (T _J = 175 °C) ^a | T _A = 25 °C | la la | 8.0 | 7.0 | А |
| Continuous Drain Current $(1_j = 175 \text{ C})$ | T _A = 70 °C | ۱ _D | 6.4 | 5.6 | |
| Pulsed Drain Current | I _{DM} | 4 | A | | |
| Avalanche Current | I _{AS} | 1 | | | |
| Single Pulse Avalanche Energy | E _{AS} | 1 | mJ | | |
| Maximum Davies Disain ation? | T _A = 25 °C | P _D | 3.3 | 1.7 | w |
| Maximum Power Dissipation ^a | T _A = 70 °C | ' D | 2.3 | 1.2 | vv |
| Operating Junction and Storage Temperature Ra | T _J , T _{stg} | - 55 t | °C | | |

| THERMAL RESISTANCE RATINGS | | | | | | | | |
|--|--------------|-------------------|---------|------|------|--|--|--|
| Parameter | Symbol | Typical | Maximum | Unit | | | | |
| Mauinum hursting to Archingt a | t ≤ 10 s | R _{thJA} | 36 | 45 | | | | |
| Maximum Junction-to-Ambient ^a | Steady State | ``thJA | 75 | 90 | °C/W | | | |
| Maximum Junction-to-Foot (Drain) | Steady State | R _{thJF} | 17 | 20 | | | | |

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | | | |
|---|---------------------|--|------|---|-------|------|--|--|--|
| Static | | | | .,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,, | | 3111 | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | 60 | | | V | | | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$ | 1 | | 3 | V | | | |
| Gate-Body Leakage | | | | | ± 100 | nA | | | |
| Zaro Cata Voltago Drain Current | I _{DSS} | $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$ | | | 1 | μA | | | |
| Zero Gate Voltage Drain Current | | V _{DS} = 60 V, V _{GS} = 0 V, T _J = 55 °C | | | 20 | | | | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$ | 40 | | | А | | | |
| | | V _{GS} = 10 V, I _D = 6.0 A | | 0.030 | | | | | |
| Drain-Source On-State Resistance ^a | P | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 6.0 \text{ A}, \text{ T}_{J} = 125 \text{ °C}$ | | 0.035 | | Ω | | | |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} = 10 V, I _D = 6.0 A, T _J = 175 °C | | 0.040 | | | | | |
| | | V _{GS} = 4.5 V, I _D = 5.1 A | | 0.034 | | | | | |
| Forward Transconductancea | 9 _{fs} | V _{DS} = 15 V, I _D = 6.0 A | | 25 | | S | | | |
| Diode Forward Voltage ^a | V _{SD} | I _S = 1.7 A, V _{GS} = 0 V | | 0.8 | 1.2 | V | | | |
| Dynamic ^b | | | | • | | | | | |
| Total Gate Charge | Qg | | | 18 | 27 | | | | |
| Gate-Source Charge | Q _{gs} | V_{DS} = 30 V, V_{GS} = 10 V, I_{D} = 6.0 A | | 3.4 | | nC | | | |
| Gate-Drain Charge | Q _{gd} | | | 5.3 | | | | | |
| Gate Resistance | Rg | V _{GS} = 0.1 V, f = 5 MHz | 0.5 | 1.4 | 2.4 | Ω | | | |
| Turn-On Delay Time | t _{d(on)} | | | 10 | 20 | | | | |
| Rise Time | t _r | V_{DD} = 30 V, R_L = 30 Ω | | 10 | 20 | ns | | | |
| Turn-Off Delay Time | t _{d(off)} | $I_{D}\cong$ 1 A, V_{GEN} = 10 V, R_{g} = 6 Ω | | 25 | 50 | | | | |
| Fall Time | t _f | | | 12 | 24 | | | | |
| Source-Drain Reverse Recovery Time | t _{rr} | I _F = 1.7 A, dl/dt = 100 A/μs | | 50 | 80 | | | | |

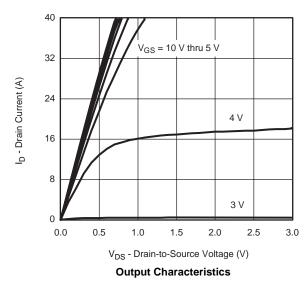
Notes:

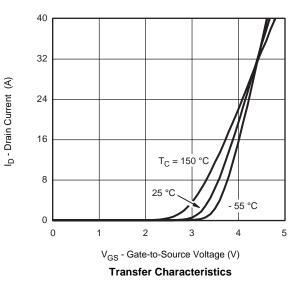
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

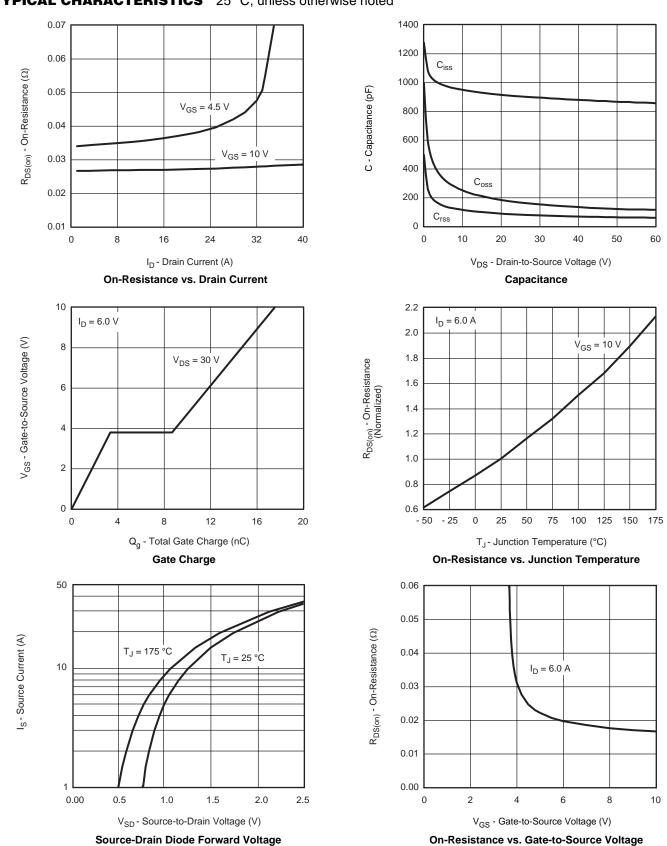
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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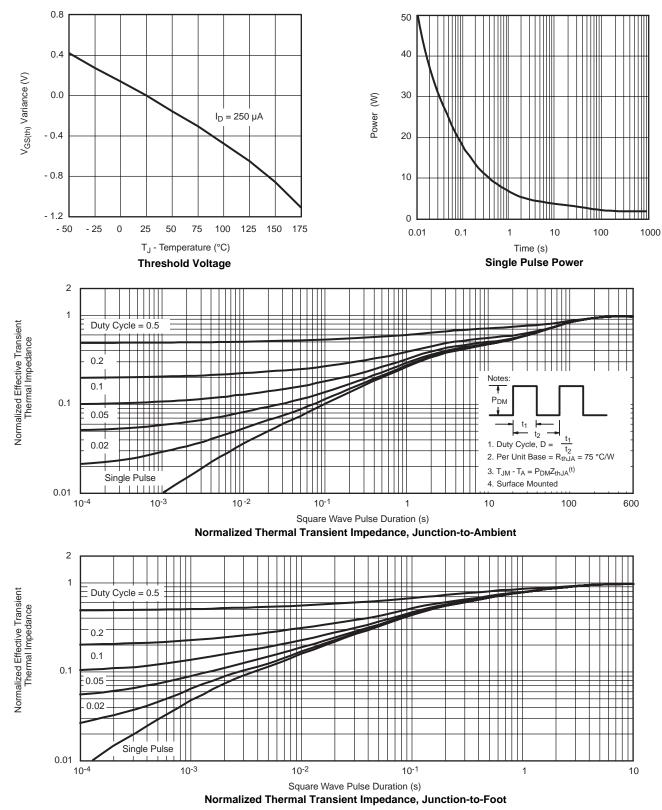




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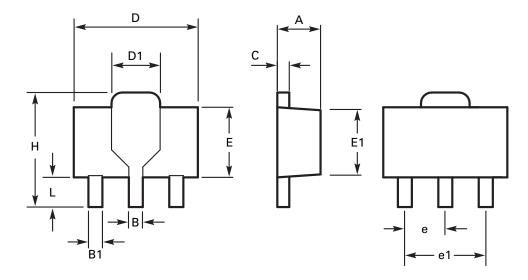








Package outline - SOT89



| DIM | Millin | neters | Inc | hes | DIM | Millimeters | | Inches | |
|-----|--------|--------|-------|-------|-----|-------------|------|-----------|-------|
| | Min | Max | Min | Max | | Min | Max | Min | Max |
| А | 1.40 | 1.60 | 0.550 | 0.630 | E | 2.29 | 2.60 | 0.090 | 0.102 |
| В | 0.44 | 0.56 | 0.017 | 0.022 | E1 | 2.13 | 2.29 | 0.084 | 0.090 |
| B1 | 0.36 | 0.48 | 0.014 | 0.019 | е | 1.50 BSC | | 0.059 BSC | |
| С | 0.35 | 0.44 | 0.014 | 0.017 | e1 | 3.00 BSC | | 0.118 BSC | |
| D | 4.40 | 4.60 | 0.173 | 0.181 | Н | 3.94 | 4.25 | 0.155 | 0.167 |
| D1 | 1.62 | 1.83 | 0.064 | 0.072 | L | 0.89 | 1.20 | 0.035 | 0.047 |

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches



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